



NOTES :

1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : C194
3. PACKAGE DIMENSION EXCLUDE MOLDING FLASH
4. AFTER SOLDER PLATING LEAD THICKNESS WILL BE 0.013" MAX
5. AFTER SOLDER DIPPING LEAD THICKNESS WILL BE 0.020" MAX
6. THE MAX. ALLOWABLE MOLDING FLASH IS 0.010"
7. TOLERANCE : 0.010" UNLESS OTHERWISE SPECIFIED
8. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPES
9. THE BOTTOM E- PIN INDENT IS MARKED AS BELOW :

L7 TAIWAN XY	X : A-T
	Y : 0-9
10. PACKAGE DIMENIONS ARE IN COMPLIANCE WITH JEDEC STANDARD MS-001 AB JUL85' ISSUE B

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	3.6	3.9	4.2	0.142	0.154	0.165
A1	0.38	—	—	0.015	—	—
A2	3.25	3.30	3.45	0.128	0.130	0.136
B	0.36	0.46	0.56	0.014	0.018	0.022
B1	1.4	1.524	1.65	0.055	0.060	0.065
B2	0.813	0.99	1.17	0.032	0.039	0.046
C	0.20	0.25	0.33	0.008	0.010	0.013
D	9.12	9.30	9.53	0.359	0.366	0.375
E	7.62	7.87	8.26	0.300	0.310	0.325
E1	6.20	6.35	6.60	0.244	0.250	0.260
e	—	2.54	—	—	0.100	—
L	3.18	—	—	0.125	—	—
eB	8.38	—	9.40	0.330	—	0.370
S	0.71	0.84	0.97	0.028	0.033	0.038

CUSTOMER :		LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z PRECISION IND, LTD TAICHUNG, TAIWAN. R. O. C		
APPROVED BY	DATE	TITLE : 8L P-DIP PACKAGE OUTLINE DRAWING		
DRAW BY: <i>Vivi Chen</i>	03/30/'99			
CHECK BY: <i>Thomas Kao</i>	04/06/'99	DWG. NO. PO-DIP-001		
APPROVAL: <i>Paul Liu</i>	04/06/'99			
APPROVAL: <i>Jack Tu</i>	04/07/'99	UNIT : INCH	SCALE : 8/1	REV. 0
		SHEET 1 OF 1		